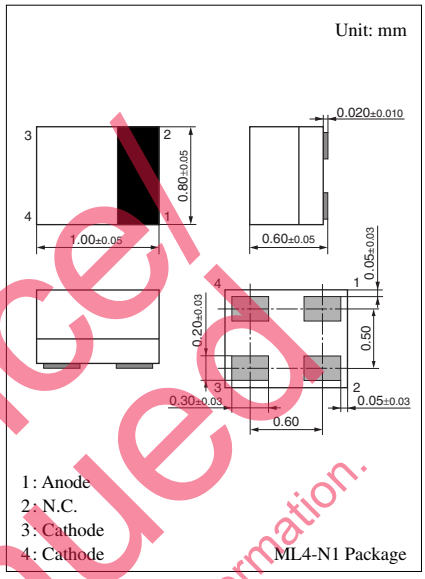
MA4L728

Silicon epitaxial planar type

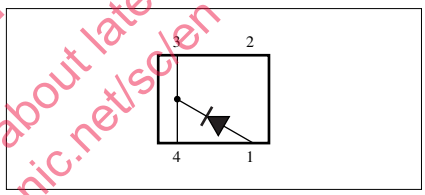
For high speed switching

For wave detection



Marking Symbol: 2

Internal Connection



■ Features

- Low forward voltage V_F and good wave detection efficiency η
- Small reverse current I_R
- Small temperature coefficient of forward characteristic
- 1008-type mold leadless 4-pin package

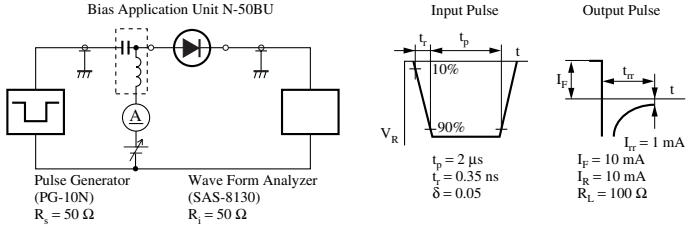
■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	30	V
Peak reverse voltage	V_{RM}	30	V
Forward current (DC)	I_F	30	mA
Peak forward current	I_{FM}	150	mA
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current (DC)	I_R	V_R = 30 V			300	nA
Forward voltage (DC)	V_{F1}	I_F = 1 mA			0.4	V
	V_{F2}	I_F = 30 mA			1.0	
Terminal capacitance	C_t	V_R = 1 V, f = 1 MHz		1.5		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 10 mA I_{rr} = 1 mA, R_L = 100 Ω		1.0		ns
Detection efficiency	η	$V_{in} = 3\ V_{(peak)}$, f = 30 MHz R_L = 3.9 Ω, C_L = 10 pF		65		%

Note) 1. This product is sensitive to electric shock (static electricity, etc.).
Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
2. Rated input/output frequency: 2 GHz 3. *: t_{rr} measuring instrument



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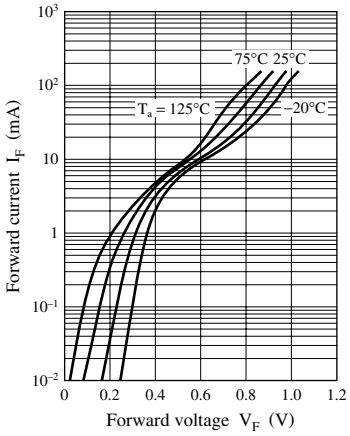
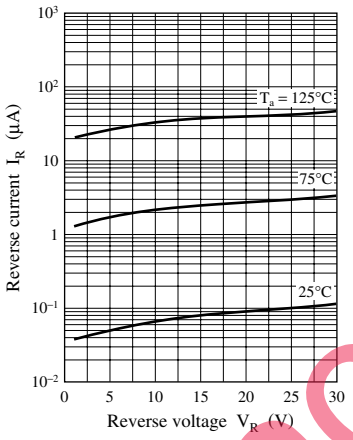
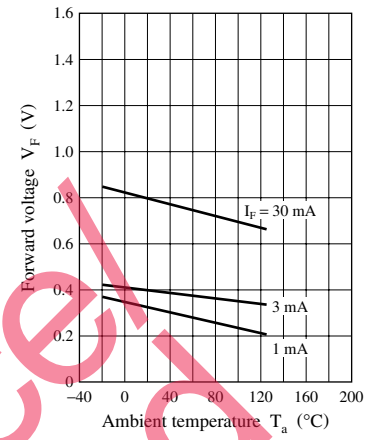
I_F — V_F



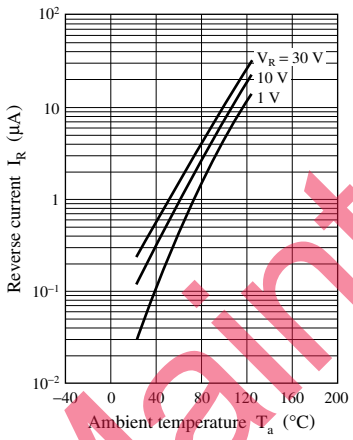
I_R — V_R



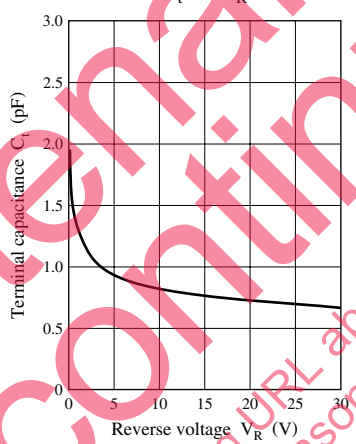
V_F — T_a



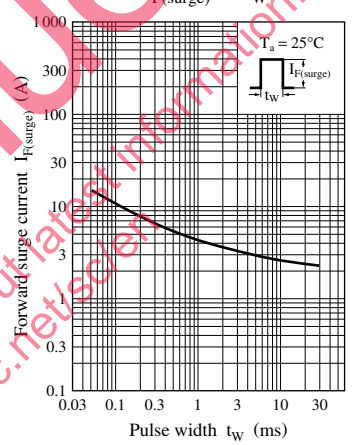
I_R — T_a



C_t — V_R



$I_{F(surge)}$ — t_W



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